

Retainer adjusted for chip 0.9 mm
+/-0.10 height
Socket for chip 0.9 to 3.5mm height

Screw
Aluminium
Torque 25cN.m

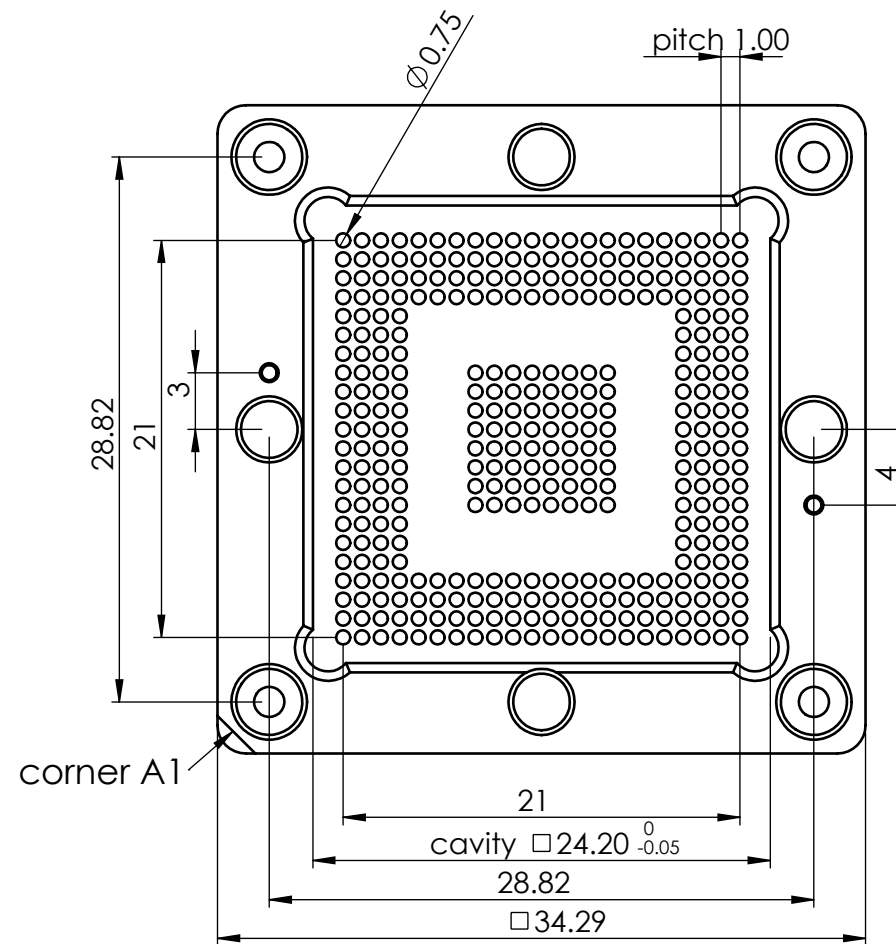
Retention frame
Polyepoxyde EGB-HT

Socket
Polyepoxyde EGB-HT

Sheet
Polyepoxyde EGB-HT

Elastomer

Assembly board
Polyepoxyde EGB-HT



Elastomer E2/pitch 1.00
Bandwith :38Ghz at -1dB
Contact force : 50gr/pin
Contact resistance : 30mOhm
Current rating : 3A/pin
Operating temperature : -40°C to +125°C
Life cycle : BGA chip 1K
Life cycle : LGA/QFN chip 2K
FastLock retainer Life cycle : 10K

A3H Scale 2.5:1 	UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS GENERAL TOLERANCES ISO 2768m	
	REV	modif:
	0	
	NAME	DATE
<small>The information contained in this drawing is proprietary to E-tec Interconnect AG and shall not be reproduced or disclosed in whole or in part or used for any design or manufacture except with the written authorization from E-tec Interconnect AG</small>	DRAWN	sme 17.09.2020
	REVD	-
	CHK'D	-
	APPV'D	sme 17.09.2020



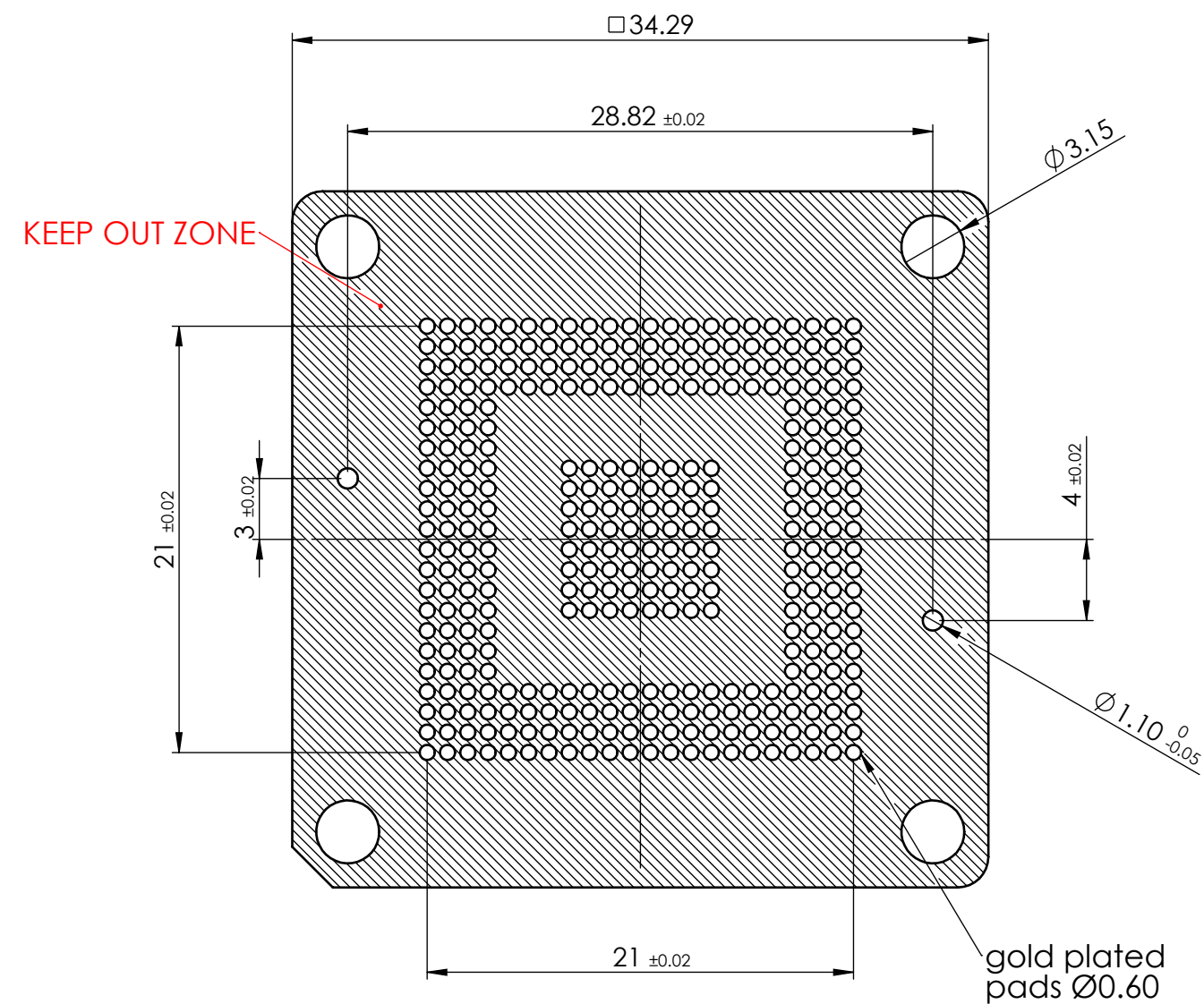
"E-tec order code"

BEF352-10E1-22AAEW55L

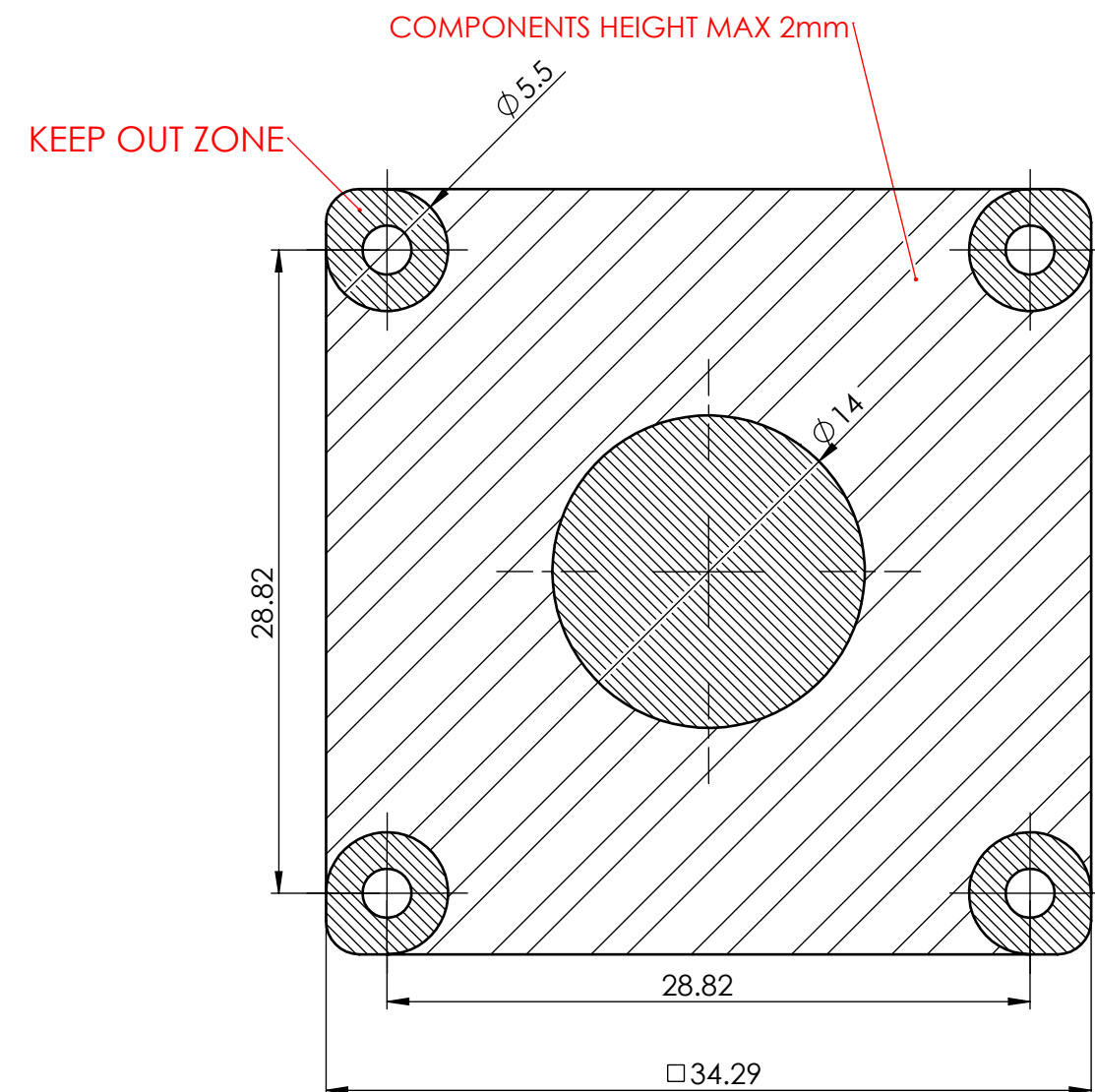
"Production code"

BEF0352-10-1010-22AAA-L

Remark:
BGA Fast Lock socket, 352pins,
Pitch 1.00mm, matrix 22x22



PCB LAYOUT
TOP VIEW



PCB LAYOUT
BOTTOM VIEW

A3H Scale 3:1 The information contained in this drawing is proprietary to E-tec Interconnect AG and shall not be reproduced or disclosed in whole or in part or used for any design or manufacture except with the written authorization from E-tec Interconnect AG.	UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS GENERAL TOLERANCES ISO 2768m		E-tec Interconnect Remark: BGA Fast Lock socket, 352pins, Pitch 1.00mm, matrix 22x22
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